

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#7 *HW*
ku Ambler
5-302

In re Patent Application of:
MAGNI ET AL.

Serial No. **Not yet assigned**

Filing Date: **Herewith**

For: **MANUFACTURING METHOD OF AN
ELECTRONIC DEVICE PACKAGE**

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INDICATED BELOW AND IS ADDRESSED TO: BOX PATENT
) APPLICATIONS, ASST. COMMISSIONER FOR PATENTS,
) WASHINGTON DC 20231-0001.

) EXPRESS MAIL NO: EL 766140226 US

) DATE OF DEPOSIT: December 26, 2001

) NAME: DAWN KIMLER

) SIGNATURE: *Dawn Kimler*

PRELIMINARY AMENDMENT

Director, U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Prior to the calculation of fees and examination of
the present application, please enter the amendments and
remarks set out below.

In the Drawings:

Submitted herewith is a request for proposed drawing
modifications as indicated in red ink to label FIGS. 1-6 as
prior art, to draw a line for reference number 13 in FIG. 7
and to label reference number 13 in FIG. 8.

In the Claims:

Please cancel ~~Claims 1 to 7.~~

Please add new Claims 8 to 25.

a
8. A method for forming a plastic protective
package for an integrated circuit, the integrated circuit
being at least partially activated from outside of the
protective package, the method comprising: